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# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









# 12-Bit, 20 MSPS/40 MSPS/65 MSPS/80 MSPS, 1.8 V Dual Analog-to-Digital Converter

Data Sheet AD9231

#### **FEATURES**

1.8 V analog supply operation 1.8 V to 3.3 V output supply SNR

71.3 dBFS at 9.7 MHz input 69.0 dBFS at 200 MHz input SFDR

93 dBc at 9.7 MHz input 83 dBc at 200 MHz input

Low power

32 mW per channel at 20 MSPS 71 mW per channel at 80 MSPS

Differential input with 700 MHz bandwidth

On-chip voltage reference and sample-and-hold circuit

2 V p-p differential analog input

 $DNL = \pm 0.40 LSB$ 

**Serial port control options** 

Offset binary, gray code, or twos complement data format

Optional clock duty cycle stabilizer

Integer 1-to-8 input clock divider

Data output multiplex option

Built-in selectable digital test pattern generation

**Energy-saving power-down modes** 

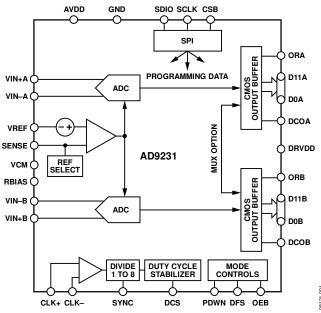
Data clock out with programmable clock and data alignment

## **APPLICATIONS**

Radar/LIDAR

Communications
Diversity radio systems
Multimode digital receivers
GSM, EDGE, W-CDMA, LTE, CDMA2000, WiMAX, TD-SCDMA
I/Q demodulation systems
Smart antenna systems
Battery-powered instruments
Hand held scope meters
Portable medical imaging
Ultrasound

### **FUNCTIONAL BLOCK DIAGRAM**



#### **PRODUCT HIGHLIGHTS**

 The AD9231 operates from a single 1.8 V analog power supply and features a separate digital output driver supply to accommodate 1.8 V to 3.3 V logic families.

Fiaure 1.

- 2. The patented sample-and-hold circuit maintains excellent performance for input frequencies up to 200 MHz and is designed for low cost, low power, and ease of use.
- A standard serial port interface supports various product features and functions, such as data output formatting, internal clock divider, power-down, DCO/DATA timing and offset adjustments, and voltage reference modes.
- 4. The AD9231 is packaged in a 64-lead RoHS compliant LFCSP that is pin compatible with the AD9268 16-bit ADC, the AD9258 14-bit ADC, the AD9251 14-bit ADC, and the AD9204 10-bit ADC, enabling a simple migration path between 10-bit and 16-bit converters sampling from 20 MSPS to 125 MSPS.

# AD9231\* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

# COMPARABLE PARTS 🖳

View a parametric search of comparable parts.

# **EVALUATION KITS**

· AD9231 Evaluation Board

# **DOCUMENTATION**

### **Application Notes**

- AN-1142: Techniques for High Speed ADC PCB Layout
- · AN-742: Frequency Domain Response of Switched-Capacitor ADCs
- AN-812: MicroController-Based Serial Port Interface (SPI) **Boot Circuit**
- AN-827: A Resonant Approach to Interfacing Amplifiers to **Switched-Capacitor ADCs**
- AN-877: Interfacing to High Speed ADCs via SPI
- · AN-878: High Speed ADC SPI Control Software
- · AN-905: Visual Analog Converter Evaluation Tool Version 1.0 User Manual
- AN-935: Designing an ADC Transformer-Coupled Front End

### **Data Sheet**

 AD9231: 12-Bit, 20 MSPS/40 MSPS/65 MSPS/80 MSPS, 1.8 V Dual Analog-to-Digital Converter Data Sheet

### **User Guides**

 UG-003: Evaluating the AD9650/AD9268/AD9258/ AD9251/AD9231/AD9204 Analog-to-Digital Converters

## TOOLS AND SIMULATIONS $\Box$



- Visual Analog
- AD9231 IBIS Models
- AD9204/AD9231/AD9251 S-Parameter Data

## REFERENCE MATERIALS 🖳

#### **Product Selection Guide**

RF Source Booklet

#### **Technical Articles**

- Improve The Design Of Your Passive Wideband ADC Front-End Network
- MS-2210: Designing Power Supplies for High Speed ADC

# DESIGN RESOURCES 🖳

- AD9231 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

# **DISCUSSIONS** •

View all AD9231 EngineerZone Discussions.

# SAMPLE AND BUY 🖳

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**Data Sheet** 

# AD9231

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# 10/2009—Revision 0: Initial Version

# **GENERAL DESCRIPTION**

The AD9231 is a monolithic, dual-channel, 1.8 V supply, 12-bit, 20 MSPS/40 MSPS/65 MSPS/80 MSPS analog-to-digital converter (ADC). It features a high performance sample-and-hold circuit and on-chip voltage reference.

The product uses multistage differential pipeline architecture with output error correction logic to provide 12-bit accuracy at 80 MSPS data rates and to guarantee no missing codes over the full operating temperature range.

The ADC contains several features designed to maximize flexibility and minimize system cost, such as programmable clock and data alignment and programmable digital test pattern generation. The available digital test patterns include built-in deterministic and pseudorandom patterns, along with custom user-defined test patterns entered via the serial port interface (SPI).

A differential clock input controls all internal conversion cycles. An optional duty cycle stabilizer (DCS) compensates for wide variations in the clock duty cycle while maintaining excellent overall ADC performance.

The digital output data is presented in offset binary, gray code, or twos complement format. A data output clock (DCO) is provided for each ADC channel to ensure proper latch timing with receiving logic. Both 1.8 V and 3.3 V CMOS levels are supported, and output data can be multiplexed onto a single output bus.

The AD9231 is available in a 64-lead RoHS compliant LFCSP and is specified over the industrial temperature range  $(-40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C})$ .

# **SPECIFICATIONS**

## **DC SPECIFICATIONS**

AVDD = 1.8 V; DRVDD = 1.8 V, maximum sample rate, 2 V p-p differential input, 1.0 V internal reference; AIN = -1.0 dBFS, and the same of theDCS disabled, unless otherwise noted.

Table 1.

		AD9231-20/AD9231-40		AD9231-65			AD9231-80				
Parameter	Temp	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
RESOLUTION	Full	12			12			12			Bits
ACCURACY											
No Missing Codes	Full		Guarante	ed	(	Guarante	ed	(	Guarante	ed	
Offset Error	Full		0.05	±0.5		0.05	±0.5		0.05	±0.5	% FSR
Gain Error <sup>1</sup>	Full		-1.5			-1.5			-1.5		% FSR
Differential Nonlinearity (DNL) <sup>2</sup>	Full			±0.30			±0.40			±0.40	LSB
	25°C		±0.12			±0.17			±0.2		LSB
Integral Nonlinearity (INL) <sup>2</sup>	Full			±0.45			±0.50			±0.65	LSB
	25°C		±0.15			±0.17			±0.2		LSB
MATCHING CHARACTERISTICS											
Offset Error	25°C		±0.0	±0.70		±0.0	±0.60		±0.0	±0.60	% FSR
Gain Error <sup>1</sup>	25°C		0.3			0.3			0.4		% FSR
TEMPERATURE DRIFT											
Offset Error	Full		±2			±2			±2		ppm/°C
INTERNAL VOLTAGE REFERENCE											
Output Voltage (1 V Mode)	Full	0.981	0.993	1.005	0.981	0.993	1.005	0.981	0.993	1.005	V
Load Regulation Error at 1.0 mA	Full		2			2			2		mV
INPUT-REFERRED NOISE											
VREF = 1.0 V	25°C		0.25			0.25			0.25		LSB rms
ANALOG INPUT											
Input Span, VREF = 1.0 V	Full		2			2			2		V p-p
Input Capacitance <sup>3</sup>	Full		6			6			6		pF
Input Common-Mode Voltage	Full		0.9			0.9			0.9		V
Input Common-Mode Range	Full	0.5		1.3	0.5		1.3	0.5		1.3	V
REFERENCE INPUT RESISTANCE	Full		7.5			7.5			7.5		kΩ
POWER SUPPLIES											
Supply Voltage											
AVDD	Full	1.7	1.8	1.9	1.7	1.8	1.9	1.7	1.8	1.9	V
DRVDD	Full	1.7		3.6	1.7		3.6	1.7		3.6	V
Supply Current											
IAVDD <sup>2</sup>	Full		35.7/49.0	37.7/52.2		69	72.4		80.0	83.4	mA
IDRVDD <sup>2</sup> (1.8 V)	Full		3.0/5.1			7.4			9.1		mA
IDRVDD <sup>2</sup> (3.3 V)	Full		5.9/10.1			14.9			18.3		mA
POWER CONSUMPTION											
DC Input	Full		63.5/87.1			122.9			141.8		mW
Sine Wave Input <sup>2</sup> (DRVDD = $1.8 \text{ V}$ )	Full		69.7/97.3	73.3/103.0		138.0	143.8		160.4	166.5	mW
Sine Wave Input <sup>2</sup> (DRVDD = $3.3 \text{ V}$ )	Full		83.7/121.5			173.4			204		mW
Standby Power <sup>4</sup>	Full		37/37			37			37		mW
Power-Down Power	Full		2.2			2.2			2.2		mW

<sup>&</sup>lt;sup>1</sup> Measured with 1.0 V external reference. <sup>2</sup> Measured with a 10 MHz input frequency at rated sample rate, full-scale sine wave, with approximately 5 pF loading on each output bit. <sup>3</sup> Input capacitance refers to the effective capacitance between one differential input pin and AGND.

<sup>&</sup>lt;sup>4</sup> Standby power is measured with a dc input and the CLK active.

## **AC SPECIFICATIONS**

AVDD = 1.8 V; DRVDD = 1.8 V, maximum sample rate, 2 V p-p differential input, 1.0 V internal reference; AIN = -1.0 dBFS, DCS disabled, unless otherwise noted.

Table 2.

	AD9231-20/AD9231-40		AD9231-65			AD9231-80					
Parameter <sup>1</sup>	Temp	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
SIGNAL-TO-NOISE RATIO (SNR)											
$f_{IN} = 9.7 \text{ MHz}$	25°C		70.7/71.5			71.4			71.3		dBFS
$f_{IN} = 30.5 MHz$	25°C		70.6/71.3			71.3			71.2		dBFS
	Full	70.1/70.7			70.5						dBFS
$f_{IN} = 70 \text{ MHz}$	25°C		70.5/71.0			71.0			70.9		dBFS
	Full							70.1			dBFS
$f_{IN} = 200 \text{ MHz}$	25°C		69.0			69.0			69.0		dBFS
SIGNAL-TO-NOISE-AND-DISTORTION (SINAD)											
$f_{IN} = 9.7 \text{ MHz}$	25°C		70.6/71.4			71.3			71.2		dBFS
$f_{IN} = 30.5 MHz$	25°C		70.6/71.2			71.2			71.1		dBFS
	Full	70.1/70.6			70.0						dBFS
$f_{IN} = 70 \text{ MHz}$	25°C		70.4/70.9			70.9			70.8		dBFS
	Full							70.0			dBFS
$f_{IN} = 200 \text{ MHz}$	25°C		68			68			68		dBFS
EFFECTIVE NUMBER OF BITS (ENOB)											
$f_{IN} = 9.7 \text{ MHz}$	25°C		11.4/11.6			11.6			11.5		Bits
$f_{IN} = 30.5 MHz$	25°C		11.4/11.5			11.5			11.5		Bits
$f_{IN} = 70 \text{ MHz}$	25°C		11.4/11.5			11.5			11.5		Bits
$f_{IN} = 200 \text{ MHz}$	25°C		11.0			11.0			11.0		Bits
WORST SECOND OR THIRD HARMONIC											
$f_{IN} = 9.7 \text{ MHz}$	25°C		-95			-95			-93		dBc
$f_{IN} = 30.5 \text{ MHz}$	25°C		-95			-95			-93		dBc
	Full			-81			-81				dBc
$f_{IN} = 70 \text{ MHz}$	25°C		-92/-94			-94			-92		dBc
	Full									-81	dBc
$f_{IN} = 200 \text{ MHz}$	25°C		-83			-83			-83		dBc
SPURIOUS-FREE DYNAMIC RANGE (SFDR)											
$f_{IN} = 9.7 \text{ MHz}$	25°C		95			95			93		dBc
$f_{IN} = 30.5 MHz$	25°C		95			95			93		dBc
	Full	81			81						dBc
$f_{IN} = 70 \text{ MHz}$	25°C		92/94			94			92		dBc
	Full							81			dBc
$f_{IN} = 200 \text{ MHz}$	25°C		83			83			83		dBc
WORST OTHER (HARMONIC OR SPUR)											
$f_{IN} = 9.7 \text{ MHz}$	25°C		-98			-98			-97		dBc
$f_{IN} = 30.5 MHz$	25°C		-97/-98			-98			-97		dBc
	Full			-90			-90				dBc
$f_{IN} = 70 \text{ MHz}$	25°C		-97/-98			-98			-95		dBc
	Full									-89	dBc
$f_{IN} = 200 \text{ MHz}$	25°C		-92			-92			-92		dBc
TWO-TONE SFDR											
$f_{IN} = 28.3 \text{ MHz} (-7 \text{ dBFS}), 30.6 \text{ MHz} (-7 \text{ dBFS})$	25°C		90			90			90		dBc
CROSSTALK <sup>2</sup>	Full		-110			-110			-110		dBc
ANALOG INPUT BANDWIDTH	25°C		700			700			700		MHz

<sup>&</sup>lt;sup>1</sup> See the AN-835 Application Note, *Understanding High Speed ADC Testing and Evaluation*, for a complete set of definitions. <sup>2</sup> Crosstalk is measured at 100 MHz with –1.0 dBFS on one channel and no input on the alternate channel.

## **DIGITAL SPECIFICATIONS**

AVDD = 1.8 V; DRVDD = 1.8 V, maximum sample rate, 2 V p-p differential input, 1.0 V internal reference; AIN = -1.0 dBFS, DCS disabled, unless otherwise noted.

Table 3.

	AD9231-20/AD9231-40/AD9231-65/AD9231-80							
Parameter	Temp	Min	Тур	Max	Unit			
DIFFERENTIAL CLOCK INPUTS (CLK+, CLK-)								
Logic Compliance			CMOS/LVDS/LV	PECL				
Internal Common-Mode Bias	Full		0.9		V			
Differential Input Voltage	Full	0.2		3.6	V p-p			
Input Voltage Range	Full	GND - 0.3		AVDD + 0.2	V			
High Level Input Current	Full	-10		+10	μΑ			
Low Level Input Current	Full	-10		+10	μΑ			
Input Resistance	Full	8	10	12	kΩ			
Input Capacitance	Full		4		рF			
LOGIC INPUTS (SCLK/DFS, SYNC, PDWN) <sup>1</sup>								
High Level Input Voltage	Full	1.2		DRVDD + 0.3	V			
Low Level Input Voltage	Full	0		0.8	V			
High Level Input Current	Full	-50		<b>-75</b>	μΑ			
Low Level Input Current	Full	-10		+10	μΑ			
Input Resistance	Full		30		kΩ			
Input Capacitance	Full		2		рF			
LOGIC INPUTS (CSB) <sup>2</sup>					1			
High Level Input Voltage	Full	1.2		DRVDD + 0.3	V			
Low Level Input Voltage	Full	0		0.8	V			
High Level Input Current	Full	-10		+10	μΑ			
Low Level Input Current	Full	40		135	μΑ			
Input Resistance	Full		26		kΩ			
Input Capacitance	Full		2		pF			
LOGIC INPUTS (SDIO¹/DCS²)								
High Level Input Voltage	Full	1.2		DRVDD + 0.3	V			
Low Level Input Voltage	Full	0		0.8	V			
High Level Input Current	Full	-10		+10	μA			
Low Level Input Current	Full	40		130	μΑ			
Input Resistance	Full	10	26	130	kΩ			
Input Capacitance	Full		5		pF			
DIGITAL OUTPUTS	T dil				Pi			
DRVDD = 3.3 V								
High Level Output Voltage, $l_{OH} = 50 \mu A$	Full	3.29			V			
High Level Output Voltage, I <sub>OH</sub> = 3.5 mA	Full	3.25			V			
Low Level Output Voltage, IoL = 1.6 mA	Full	ر ۲۰۲۵		0.2	V			
Low Level Output Voltage, IoL = 1.0 πA	Full			0.05	V			
DRVDD = 1.8 V	l uii			0.03	*			
High Level Output Voltage, $l_{OH} = 50 \mu A$	Full	1.79			V			
High Level Output Voltage, I <sub>OH</sub> = 50 μA  High Level Output Voltage, I <sub>OH</sub> = 0.5 mA	Full	1.79			V			
Low Level Output Voltage, $I_{OL} = 0.5 \text{ mA}$	Full	1.75		0.2	V			
Low Level Output Voltage, $I_{OL} = 1.6 \text{ mA}$	Full				V			
LOW Level Output voltage, $10L = 50  \mu A$	ruii			0.05	٧			

 $<sup>^1</sup>$  Internal 30 k $\Omega$  pull-down.  $^2$  Internal 30 k $\Omega$  pull-up.

## **SWITCHING SPECIFICATIONS**

Table 4.

		AD9	231-20/AD9	231-40	A	D9231-	65	Α	D9231-	-80	
Parameter	Temp	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
CLOCK INPUT PARAMETERS											
Input Clock Rate	Full			625			625			625	MHz
Conversion Rate <sup>1</sup>	Full	3		20/40	3		65	3		80	MSPS
CLK Period—Divide-by-1 Mode (tclk)	Full	50/25			15.38			12.5			ns
CLK Pulse Width High (tcH)			25.0/12.5			7.69			6.25		ns
Aperture Delay (t <sub>A</sub> )	Full		1.0			1.0			1.0		ns
Aperture Uncertainty (Jitter, t <sub>.</sub> )	Full		0.1			0.1			0.1		ps rms
DATA OUTPUT PARAMETERS											
Data Propagation Delay (tpd)	Full		3			3			3		ns
DCO Propagation Delay (t <sub>DCO</sub> )	Full		3			3			3		ns
DCO to Data Skew (tskew)	Full		0.1			0.1			0.1		ns
Pipeline Delay (Latency)	Full		9			9			9		Cycles
Wake-Up Time <sup>2</sup>	Full		350			350			350		μs
Standby	Full		600/400			300			260		ns
OUT-OF-RANGE RECOVERY TIME	Full		2			2			2		Cycles

<sup>&</sup>lt;sup>1</sup> Conversion rate is the clock rate after the CLK divider.

 $<sup>^{\</sup>rm 2}$  Wake-up time is dependent on the value of the decoupling capacitors.

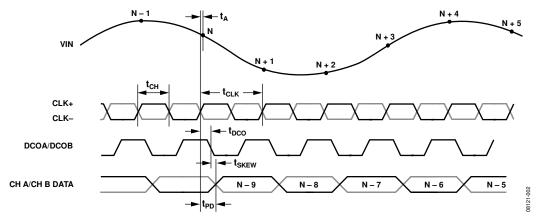


Figure 2. CMOS Output Data Timing

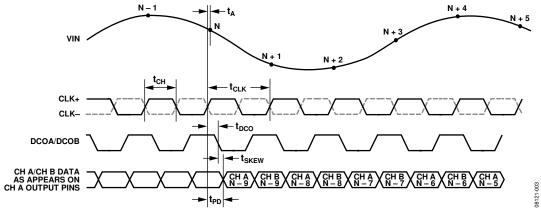


Figure 3. CMOS Interleaved Output Timing, Output as Appears on Channel A Output Pins

## **TIMING SPECIFICATIONS**

Table 5.

Parameter	Conditions	Min	Тур	Max	Unit
SYNC TIMING REQUIREMENTS					
tssync	SYNC to rising edge of CLK setup time		0.24		ns
thsync	SYNC to rising edge of CLK hold time		0.40		ns
SPI TIMING REQUIREMENTS					
$t_{DS}$	Setup time between the data and the rising edge of SCLK	2			ns
t <sub>DH</sub>	Hold time between the data and the rising edge of SCLK	2			ns
$t_CLK$	Period of the SCLK	40			ns
ts	Setup time between CSB and SCLK	2			ns
t <sub>H</sub>	Hold time between CSB and SCLK	2			ns
<b>t</b> HIGH	SCLK pulse width high	10			ns
$t_{LOW}$	SCLK pulse width low	10			ns
t <sub>en_sdio</sub>	Time required for the SDIO pin to switch from an input to an output relative to the SCLK falling edge	10			ns
t <sub>DIS_SDIO</sub>	Time required for the SDIO pin to switch from an output to an input relative to the SCLK rising edge	10			ns

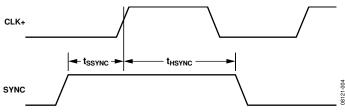


Figure 4. SYNC Input Timing Requirements

# **ABSOLUTE MAXIMUM RATINGS**

Table 6.

Parameter	Rating
AVDD to AGND	-0.3 V to +2.0 V
DRVDD to AGND	−0.3 V to +3.9 V
VIN+A, VIN+B, VIN-A, VIN-B to AGND	-0.3 V to AVDD + 0.2 V
CLK+, CLK- to AGND	-0.3 V to AVDD + 0.2 V
SYNC to AGND	-0.3 V to DRVDD + 0.3 V
VREF to AGND	-0.3 V to AVDD + 0.2 V
SENSE to AGND	-0.3 V to AVDD + 0.2 V
VCM to AGND	-0.3 V to AVDD + 0.2 V
RBIAS to AGND	-0.3 V to AVDD + 0.2 V
CSB to AGND	-0.3 V to DRVDD + 0.3 V
SCLK/DFS to AGND	-0.3 V to DRVDD + 0.3 V
SDIO/DCS to AGND	-0.3 V to DRVDD + 0.3 V
OEB to AGND	-0.3 V to DRVDD + 0.3 V
PDWN to AGND	-0.3 V to DRVDD + 0.3 V
D0A/D0B through D11A/D11B to AGND	-0.3 V to DRVDD + 0.3 V
DCOA/DCOB to AGND	-0.3 V to DRVDD + 0.3 V
Operating Temperature Range (Ambient)	-40°C to +85°C
Maximum Junction Temperature Under Bias	150°C
Storage Temperature Range (Ambient)	−65°C to +150°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

### THERMAL CHARACTERISTICS

The exposed paddle is the only ground connection for the chip. The exposed paddle must be soldered to the AGND plane of the user's circuit board. Soldering the exposed paddle to the user's board also increases the reliability of the solder joints and maximizes the thermal capability of the package.

**Table 7. Thermal Resistance** 

_	Package Type	Airflow Velocity (m/sec)	θ <sub>JA</sub> 1,2	<b>θ</b> <sub>JC</sub> <sup>1,3</sup>	θ <sub>JB</sub> 1,4	Unit
	64-Lead LFCSP	0	23	2.0		°C/W
	9 mm × 9 mm	1.0	20		12	°C/W
	(CP-64-4)	2.5	18			°C/W

<sup>&</sup>lt;sup>1</sup> Per JEDEC 51-7, plus JEDEC 25-5 2S2P test board.

Typical  $\theta_{JA}$  is specified for a 4-layer PCB with a solid ground plane. As shown in Table 7, airflow improves heat dissipation, which reduces  $\theta_{JA}$ . In addition, metal in direct contact with the package leads from metal traces, through holes, ground, and power planes, reduces the  $\theta_{JA}$ .

### **ESD CAUTION**



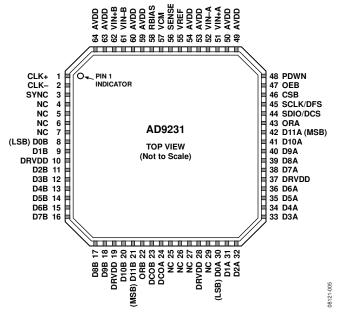
**ESD** (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

<sup>&</sup>lt;sup>2</sup> Per JEDEC JESD51-2 (still air) or JEDEC JESD51-6 (moving air).

<sup>&</sup>lt;sup>3</sup> Per MIL-Std 883, Method 1012.1.

<sup>&</sup>lt;sup>4</sup> Per JEDEC JESD51-8 (still air).

# PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



NOTES

Figure 5. Pin Configuration

**Table 8. Pin Function Description** 

Pin No.	Mnemonic	Description
0	GND	Exposed paddle is the only ground connection for the chip. Must be connected to PCB AGND.
1, 2	CLK+, CLK-	Differential Encode Clock. PECL, LVDS, or 1.8 V CMOS inputs.
3	SYNC	Digital Input. SYNC input to clock divider. 30 kΩ internal pull-down.
4, 5, 6, 7, 25, 26, 27, 29	NC	Do Not Connect.
8 to 9, 11 to 18, 20, 21	D0B to D11B	Channel B Digital Outputs. D11B = MSB.
10, 19, 28, 37	DRVDD	Digital Output Driver Supply (1.8 V to 3.3 V).
22	ORB	Channel B Out-of-Range Digital Output.
23	DCOB	Channel B Data Clock Digital Output.
24	DCOA	Channel A Data Clock Digital Output.
30 to 36, 38 to 42	D0A to D11A	Channel A Digital Outputs. D11A = MSB.
43	ORA	Channel A Out-of-Range Digital Output.
44	SDIO/DCS	SPI Data Input/Output (SDIO). Bidirectional SPI Data I/O in SPI mode. 30 k $\Omega$ internal pull-down in SPI mode. Duty Cycle Stabilizer (DCS). Static enable input for duty cycle stabilizer in non-SPI mode. 30 k $\Omega$ internal pull-up in non-SPI (DCS) mode.
45	SCLK/DFS	SPI Clock (SCLK) Input in SPI mode. 30 k $\Omega$ internal pull-down. Data Format Select (DFS). Static control of data output format in non-SPI mode. 30 k $\Omega$ internal pull-down. DFS high = twos complement output. DFS low = offset binary output.
46	CSB	SPI Chip Select. Active low enable; 30 kΩ internal pull-up.
47	OEB	Digital Input. Enable Channel A and Channel B digital outputs if low, tristate outputs if high. $30 \text{ k}\Omega$ internal pull-down.
48	PDWN	Digital Input. 30 k $\Omega$ internal pull-down. PDWN high = power-down device. PDWN low = run device, normal operation.

<sup>1.</sup> NC = NO CONNECT.

2. THE EXPOSED PADDLE MUST BE SOLDERED TO THE PCB GROUND TO ENSURE PROPER HEAT DISSIPATION, NOISE, AND MECHANICAL STRENGTH BENEFITS.

Pin No.	Mnemonic	Description
49, 50, 53, 54, 59, 60, 63, 64	AVDD	1.8 V Analog Supply Pins.
51, 52	VIN+A, VIN-A	Channel A Analog Inputs.
55	VREF	Voltage Reference Input/Output.
56	SENSE	Reference Mode Selection.
57	VCM	Analog output voltage at midsupply to set common mode of the analog inputs.
58	RBIAS	Sets Analog Current Bias. Connect to $10 \text{ k}\Omega$ (1% tolerance) resistor to ground.
61, 62	VIN-B, VIN+B	Channel B Analog Inputs.

# TYPICAL PERFORMANCE CHARACTERISTICS

### AD9231-80

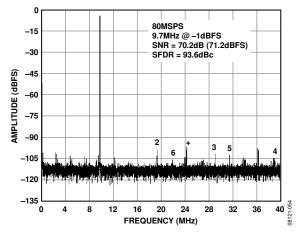


Figure 6. AD9231-80 Single-Tone FFT with  $f_{IN} = 9.7$  MHz

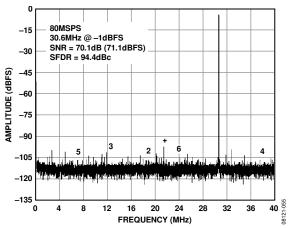


Figure 7. AD9231-80 Single-Tone FFT with  $f_{IN} = 30.6 \text{ MHz}$ 

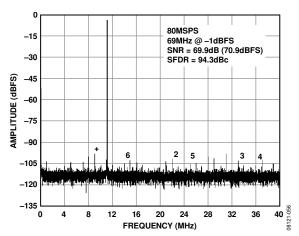


Figure 8. AD9231-80 Single-Tone FFT with  $f_{IN} = 69 \text{ MHz}$ 

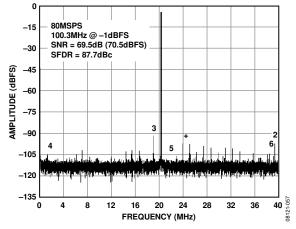


Figure 9. AD9231-80 Single-Tone FFT with  $f_{IN} = 100.3$  MHz

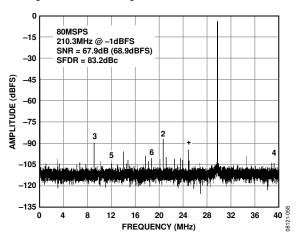


Figure 10. AD9231-80 Single-Tone FFT with  $f_{IN} = 210.3 \text{ MHz}$ 

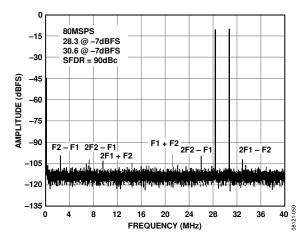


Figure 11. AD9231-80 Two-Tone FFT with  $f_{IN1} = 28.3$  MHz and  $f_{IN2} = 30.6$  MHz

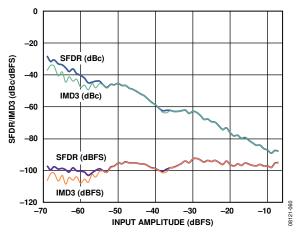


Figure 12. Two-Tone SFDR/IMD3 vs. Input Amplitude (AIN) with  $f_{\rm IN1}=28.3$  MHz and  $f_{\rm IN2}=30.6$  MHz

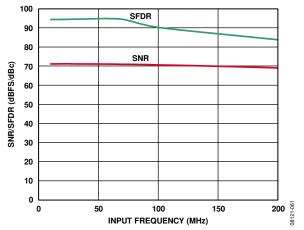


Figure 13. AD9231-80 SNR/SFDR vs. Input Frequency (AIN) with  $2\,V\,p$ -p Full Scale

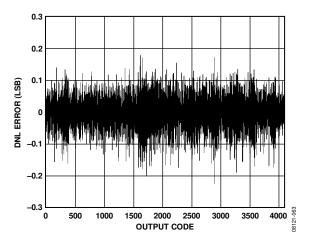


Figure 14. AD9231-80 DNL Error with  $f_{\rm IN}$  = 9.7 MHz

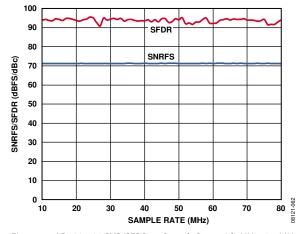


Figure 15. AD9231-80 SNR/SFDR vs. Sample Rate with AIN =  $9.7 \, \text{MHz}$ 

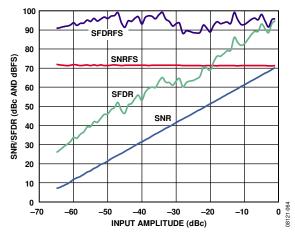


Figure 16. AD9231-80 SNR/SFDR vs. Input Amplitude (AIN) with  $f_{IN} = 9.7$  MHz

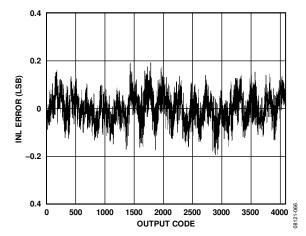


Figure 17. AD9231-80 INL with  $f_{IN} = 9.7 \text{ MHz}$ 

### AD9231-65

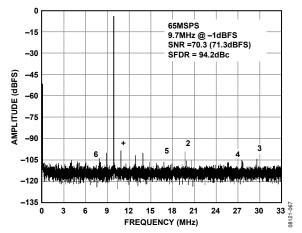


Figure 18. AD9231-65 Single-Tone FFT with  $f_{IN} = 9.7$  MHz

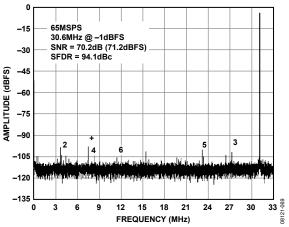


Figure 19. AD9231-65 Single-Tone FFT with  $f_{IN} = 30.6$  MHz

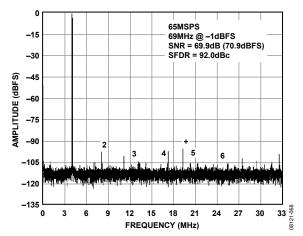


Figure 20. AD9231-65 Single-Tone FFT with  $f_{\rm IN}$  = 69 MHz

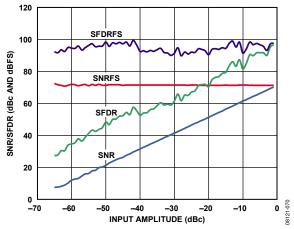


Figure 21. AD9231-65 SNR/SFDR vs. Input Amplitude (AIN) with  $f_{\rm IN} = 9.7$  MHz

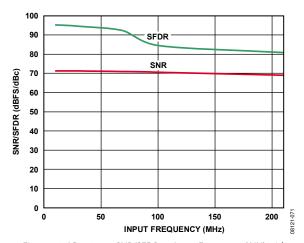


Figure 22. AD9231-65 SNR/SFDR vs. Input Frequency (AIN) with 2 V p-p Full Scale

## AD9231-40

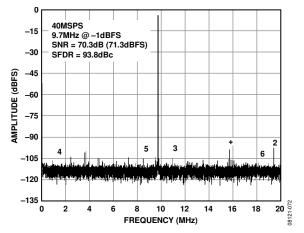


Figure 23. AD9231-40 Single-Tone FFT with  $f_{IN} = 9.7$  MHz

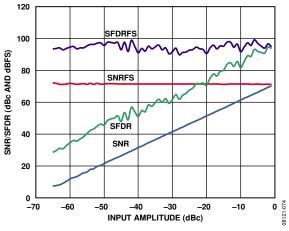


Figure 25. AD9231-40 SNR/SFDR vs. Input Amplitude (AIN) with  $f_{IN} = 9.7$  MHz

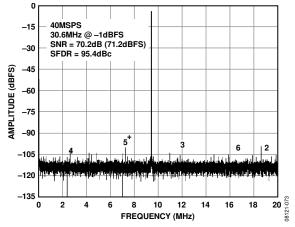


Figure 24. AD9231-40 Single-Tone FFT with  $f_{IN}$  = 30.6 MHz

120

## AD9231-20

AVDD = 1.8 V; DRVDD = 1.8 V, maximum sample rate, 2 V p-p differential input, 1.0 V internal reference; AIN = -1.0 dBFS, DCS disabled, unless otherwise noted.

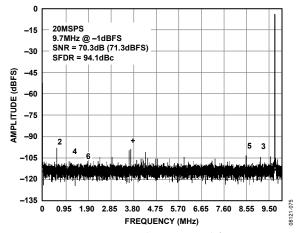
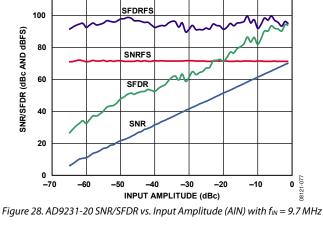


Figure 26. AD9231-20 Single-Tone FFT with  $f_{IN} = 9.7 \text{ MHz}$ 



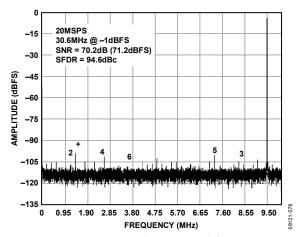


Figure 27. AD9231-20 Single-Tone FFT with  $f_{\text{IN}}$  = 30.6 MHz

# **EQUIVALENT CIRCUITS**

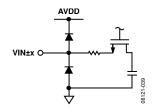


Figure 29. Equivalent Analog Input Circuit

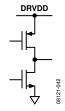


Figure 32. Equivalent Digital Output Circuit

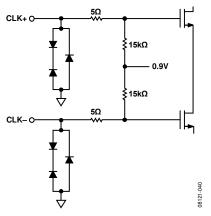


Figure 30. Equivalent Clock Input Circuit

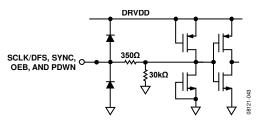


Figure 33. Equivalent SCLK/DFS, SYNC, OEB, and PDWN Input Circuit

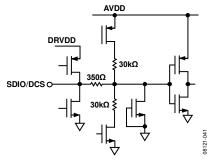


Figure 31. Equivalent SDIO/DCS Input Circuit

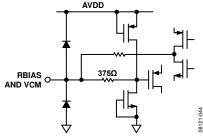


Figure 34. Equivalent RBIAS and VCM Circuit

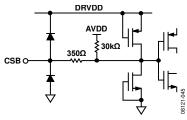


Figure 35. Equivalent CSB Input Circuit

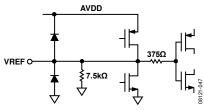


Figure 37. Equivalent VREF Circuit

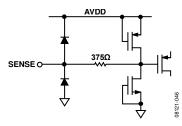


Figure 36. Equivalent SENSE Circuit

# THEORY OF OPERATION

The AD9231 dual ADC design can be used for diversity reception of signals, where the ADCs are operating identically on the same carrier but from two separate antennae. The ADCs can also be operated with independent analog inputs. The user can sample any  $f_s/2$  frequency segment from dc to 200 MHz, using appropriate low-pass or band-pass filtering at the ADC inputs with little loss in ADC performance. Operation to 300 MHz analog input is permitted but occurs at the expense of increased ADC noise and distortion.

In nondiversity applications, the AD9231 can be used as a baseband or direct downconversion receiver, where one ADC is used for I input data and the other is used for Q input data.

Synchronization capability is provided to allow synchronized timing between multiple channels or multiple devices.

Programming and control of the AD9231 is accomplished using a 3-bit SPI-compatible serial interface.

### **ADC ARCHITECTURE**

The AD9231 architecture consists of a multistage, pipelined ADC. Each stage provides sufficient overlap to correct for flash errors in the preceding stage. The quantized outputs from each stage are combined into a final 12-bit result in the digital correction logic. The pipelined architecture permits the first stage to operate with a new input sample while the remaining stages operate with preceding samples. Sampling occurs on the rising edge of the clock.

Each stage of the pipeline, excluding the last, consists of a low resolution flash ADC connected to a switched-capacitor DAC and an interstage residue amplifier (for example, a multiplying digital-to-analog converter (MDAC)). The residue amplifier magnifies the difference between the reconstructed DAC output and the flash input for the next stage in the pipeline. One bit of redundancy is used in each stage to facilitate digital correction of flash errors. The last stage simply consists of a flash ADC.

The output staging block aligns the data, corrects errors, and passes the data to the CMOS output buffers. The output buffers are powered from a separate (DRVDD) supply, allowing adjustment of the output voltage swing. During power-down, the output buffers go into a high impedance state.

### ANALOG INPUT CONSIDERATIONS

The analog input to the AD9231 is a differential switched-capacitor circuit designed for processing differential input signals. This circuit can support a wide common-mode range while maintaining excellent performance. By using an input common-mode voltage of midsupply, users can minimize signal-dependent errors and achieve optimum performance.

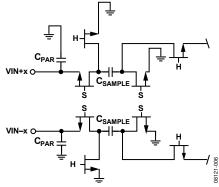


Figure 38. Switched-Capacitor Input Circuit

The clock signal alternately switches the input circuit between sample-and-hold mode (see Figure 38). When the input circuit is switched to sample mode, the signal source must be capable of charging the sample capacitors and settling within one-half of a clock cycle. A small resistor in series with each input can help reduce the peak transient current injected from the output stage of the driving source. In addition, low Q inductors or ferrite beads can be placed on each leg of the input to reduce high differential capacitance at the analog inputs and, therefore, achieve the maximum bandwidth of the ADC. Such use of low Q inductors or ferrite beads is required when driving the converter front end at high IF frequencies. Either a shunt capacitor or two single-ended capacitors can be placed on the inputs to provide a matching passive network. This ultimately creates a low-pass filter at the input to limit unwanted broadband noise. See the AN-742 Application Note, the AN-827 Application Note, and the Analog Dialogue article "Transformer-Coupled Front-End for Wideband A/D Converters" (Volume 39, April 2005) for more information. In general, the precise values depend on the application.

#### **Input Common Mode**

The analog inputs of the AD9231 are not internally dc-biased. Therefore, in ac-coupled applications, the user must provide a dc bias externally. Setting the device so that VCM = AVDD/2 is recommended for optimum performance, but the device can function over a wider range with reasonable performance, as shown in Figure 39 and Figure 40.

An on-board, common-mode voltage reference is included in the design and is available from the VCM pin. The VCM pin must be decoupled to ground by a 0.1  $\mu F$  capacitor, as described in the Applications Information section.

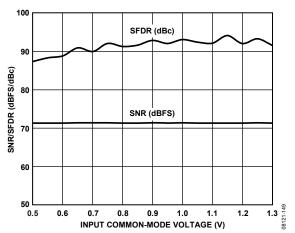


Figure 39. SNR/SFDR vs. Input Common-Mode Voltage,  $f_{IN} = 32.1$  MHz,  $f_{S} = 80$  MSPS

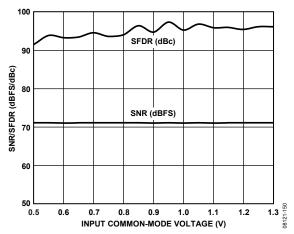


Figure 40. SNR/SFDR vs. Input Common-Mode Voltage,  $f_{IN} = 10.3 \text{ MHz}, f_S = 20 \text{ MSPS}$ 

### **Differential Input Configurations**

Optimum performance is achieved while driving the AD9231 in a differential input configuration. For baseband applications, the AD8138, ADA4937-2, and ADA4938-2 differential drivers provide excellent performance and a flexible interface to the ADC.

The output common-mode voltage of the ADA4938-2 is easily set with the VCM pin of the AD9231 (see Figure 41), and the driver can be configured in a Sallen-Key filter topology to provide band limiting of the input signal.

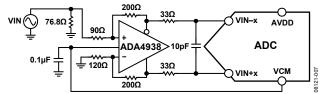


Figure 41. Differential Input Configuration Using the ADA4938-2

For baseband applications below ~10 MHz where SNR is a key parameter, differential transformer-coupling is the recommended input configuration. An example is shown in Figure 42. To bias the analog input, the VCM voltage can be connected to the center tap of the secondary winding of the transformer.

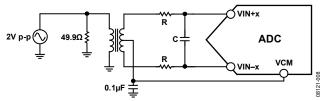


Figure 42. Differential Transformer-Coupled Configuration

The signal characteristics must be considered when selecting a transformer. Most RF transformers saturate at frequencies below a few megahertz (MHz). Excessive signal power can also cause core saturation, which leads to distortion.

At input frequencies in the second Nyquist zone and above, the noise performance of most amplifiers is not adequate to achieve the true SNR performance of the AD9231. For applications above ~10 MHz where SNR is a key parameter, differential double balun coupling is the recommended input configuration (see Figure 44).

An alternative to using a transformer-coupled input at frequencies in the second Nyquist zone is to use the AD8352 differential driver. An example is shown in Figure 45. See the AD8352 data sheet for more information.

In any configuration, the value of Shunt Capacitor C is dependent on the input frequency and source impedance and may need to be reduced or removed. Table 9 displays the suggested values to set the RC network. However, these values are dependent on the input signal and should be used only as a starting guide.

Table 9. Example RC Network

Frequency Range (MHz)	R Series (Ω Each)	C Differential (pF)
0 to 70	33	22
70 to 200	125	Open

### **Single-Ended Input Configuration**

A single-ended input can provide adequate performance in cost-sensitive applications. In this configuration, SFDR and distortion performance degrade due to the large input commonmode swing. If the source impedances on each input are matched, there should be little effect on SNR performance. Figure 43 shows a typical single-ended input configuration.

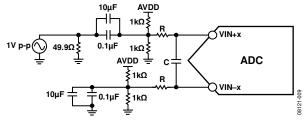


Figure 43. Single-Ended Input Configuration

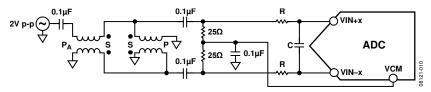


Figure 44. Differential Double Balun Input Configuration

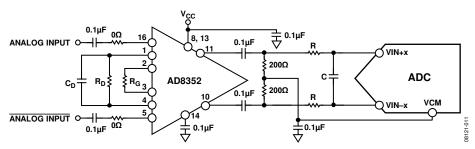


Figure 45. Differential Input Configuration Using the AD8352

#### **VOLTAGE REFERENCE**

A stable and accurate 1.0 V voltage reference is built into the AD9231. The VREF can be configured using either the internal 1.0 V reference or an externally applied 1.0 V reference voltage. The various reference modes are summarized in the sections that follow. The Reference Decoupling section describes the best practices PCB layout of the reference.

### **Internal Reference Connection**

A comparator within the AD9231 detects the potential at the SENSE pin and configures the reference into two possible modes, which are summarized in Table 10. If SENSE is grounded, the reference amplifier switch is connected to the internal resistor divider (see Figure 46), setting VREF to 1.0 V.

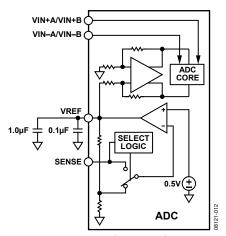


Figure 46. Internal Reference Configuration

If the internal reference of the AD9231 is used to drive multiple converters to improve gain matching, the loading of the reference by the other converters must be considered. Figure 47 shows how the internal reference voltage is affected by loading.

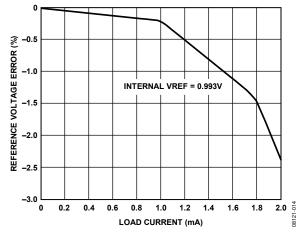


Figure 47. VREF Accuracy vs. Load Current

**Table 10. Reference Configuration Summary** 

Selected Mode	SENSE Voltage (V)	Resulting VREF (V)	Resulting Differential Span (V p-p)
Fixed Internal Reference	AGND to 0.2	1.0 internal	2.0
Fixed External Reference	AVDD	1.0 applied to external VREF pin	2.0

### **External Reference Operation**

The use of an external reference may be necessary to enhance the gain accuracy of the ADC or improve thermal drift characteristics. Figure 48 shows the typical drift characteristics of the internal reference in 1.0 V mode.

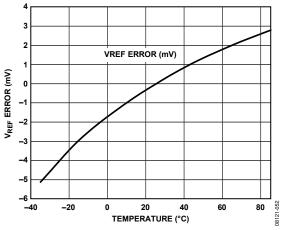


Figure 48. Typical VREF Drift

When the SENSE pin is tied to AVDD, the internal reference is disabled, allowing the use of an external reference. An internal reference buffer loads the external reference with an equivalent 7.5 k $\Omega$  load (see Figure 37). The internal buffer generates the positive and negative full-scale references for the ADC core. Therefore, the external reference must be limited to a maximum of 1.0 V.

### **CLOCK INPUT CONSIDERATIONS**

For optimum performance, clock the AD9231 sample clock inputs, CLK+ and CLK-, with a differential signal. The signal is typically ac-coupled into the CLK+ and CLK- pins via a transformer or capacitors. These pins are biased internally (see Figure 49) and require no external bias.

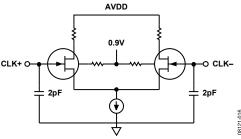


Figure 49. Equivalent Clock Input Circuit

#### **Clock Input Options**

The AD9231 has a very flexible clock input structure. The clock input can be a CMOS, LVDS, LVPECL, or sine wave signal. Regardless of the type of signal being used, clock source jitter is of the most concern, as described in the Jitter Considerations section.

Figure 50 and Figure 51 show two preferred methods for clocking the AD9231 (at clock rates up to 625 MHz). A low jitter clock source is converted from a single-ended signal to a differential signal using either an RF transformer or an RF balun.

The RF balun configuration is recommended for clock frequencies between 125 MHz and 625 MHz, and the RF transformer is recommended for clock frequencies from 10 MHz to 200 MHz. The back-to-back Schottky diodes across the transformer/balun secondary limit clock excursions into the AD9231 to approximately 0.8 V p-p differential.

This limit helps prevent the large voltage swings of the clock from feeding through to other portions of the AD9231 while preserving the fast rise and fall times of the signal that are critical to a low jitter performance.

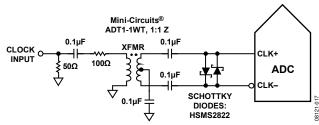


Figure 50. Transformer-Coupled Differential Clock (Up to 200 MHz)

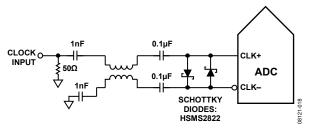


Figure 51. Balun-Coupled Differential Clock (Up to 625 MHz)

If a low jitter clock source is not available, another option is to ac couple a differential PECL signal to the sample clock input pins, as shown in Figure 52. The AD9510/AD9511/AD9512/AD9513/AD9514/AD9515/AD9516/AD9517 clock drivers offer excellent jitter performance.

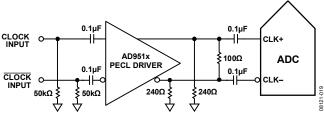


Figure 52. Differential PECL Sample Clock (Up to 625 MHz)

A third option is to ac couple a differential LVDS signal to the sample clock input pins, as shown in Figure 53. The AD9510/AD9511/AD9512/AD9513/AD9514/AD9515/AD9516/AD9517 clock drivers offer excellent jitter performance.

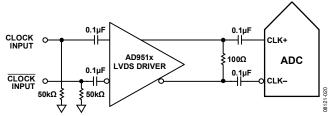


Figure 53. Differential LVDS Sample Clock (Up to 625 MHz)

In some applications, it may be acceptable to drive the sample clock inputs with a single-ended 1.8 V CMOS signal. In such applications, drive the CLK+ pin directly from a CMOS gate, and bypass the CLK– pin to ground with a 0.1  $\mu F$  capacitor (see Figure 54).

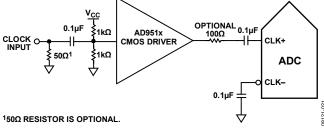


Figure 54. Single-Ended 1.8 V CMOS Input Clock (Up to 200 MHz)

#### Input Clock Divider

The AD9231 contains an input clock divider with the ability to divide the input clock by integer values between 1 and 8. Optimum performance is obtained by enabling the internal duty cycle stabilizer (DCS) when using divide ratios other than 1, 2, or 4.

The AD9231 clock divider can be synchronized using the external SYNC input. Bit 1 and Bit 2 of Register 0x100 allow the clock divider to be resynchronized on every SYNC signal or only on the first SYNC signal after the register is written. A valid SYNC causes the clock divider to reset to its initial state. This synchronization feature allows multiple parts to have their clock dividers aligned to guarantee simultaneous input sampling.

### **Clock Duty Cycle**

Typical high speed ADCs use both clock edges to generate a variety of internal timing signals and, as a result, may be sensitive to clock duty cycle. Commonly, a  $\pm 5\%$  tolerance is required on the clock duty cycle to maintain dynamic performance characteristics.

The AD9231 contains a duty cycle stabilizer (DCS) that retimes the nonsampling (falling) edge, providing an internal clock signal with a nominal 50% duty cycle. This allows the user to provide a wide range of clock input duty cycles without affecting the performance of the AD9231. Noise and distortion performance are nearly flat for a wide range of duty cycles with the DCS on, as shown in Figure 55.

Jitter in the rising edge of the input is still of concern and is not easily reduced by the internal stabilization circuit. The duty cycle control loop does not function for clock rates less than 20 MHz nominally. The loop has a time constant associated with it that must be considered in applications in which the clock rate can change dynamically. A wait time of 1.5  $\mu s$  is required after a dynamic clock frequency increase or decrease before the DCS loop is relocked to the input signal.

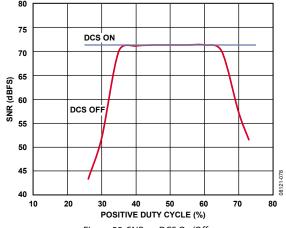


Figure 55. SNR vs. DCS On/Off